ABSTRACT

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH ROUTABLE CIRCUITRY AND METHOD OF MANUFACTURE THEREOF

An integrated circuit packaging system, and a method of manufacture therefor, including: electrical terminals; circuitry protective material around the electrical terminals and formed to have recessed pad volumes; routable circuitry on the top surface of the circuitry protective material; and an integrated circuit die electrically connected to the electrical terminals.

(Fig. 1)